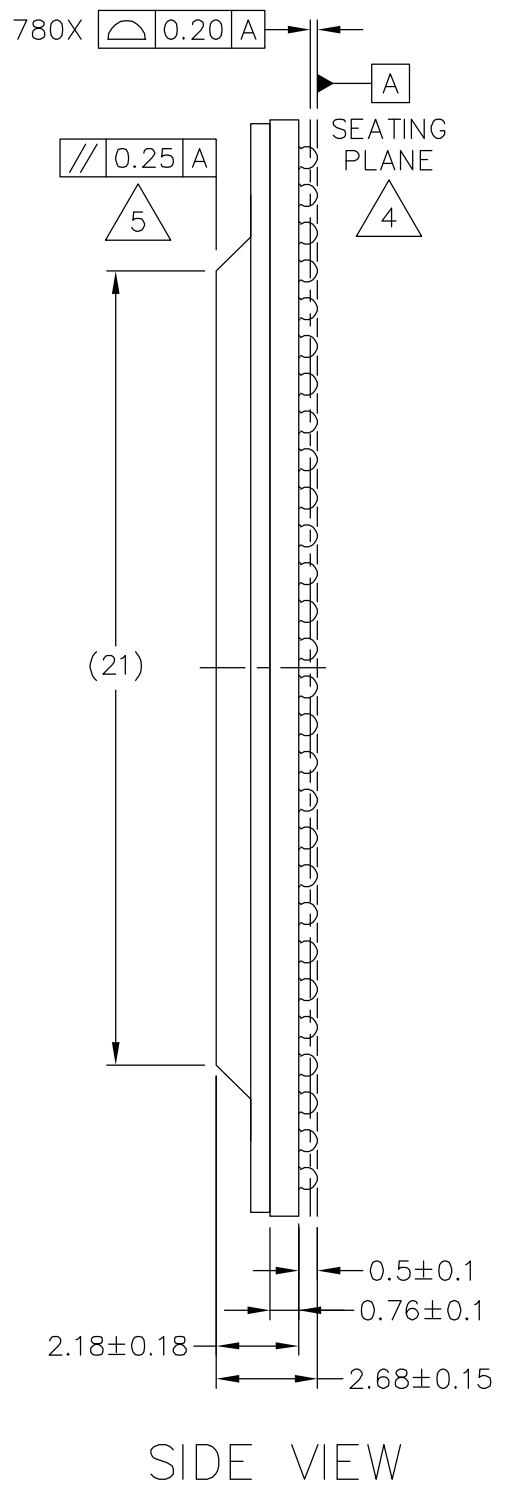
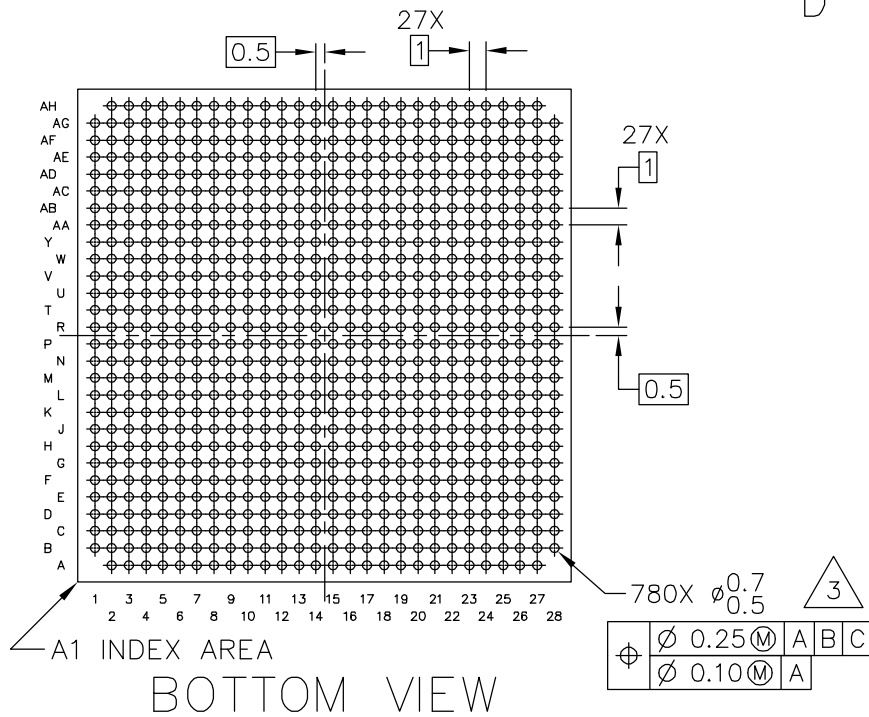
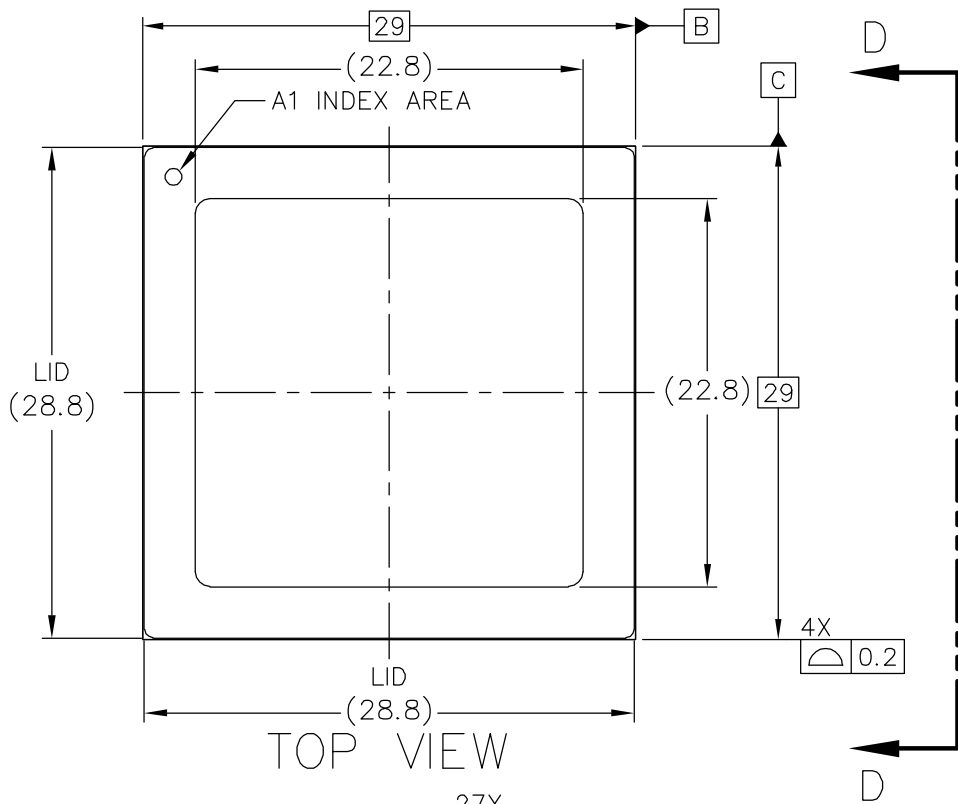




© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: FCPBGA, 29 X 29 PKG, 1 MM PITCH, 780 I/O WITH LID	DOCUMENT NO: 98ASA00465D		REV: 0
	CASE NUMBER: 2290-01		10 MAY 2012
	STANDARD: NON-JEDEC		

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE: FCPBGA, 29 X 29 PKG, 1 MM PITCH, 780 I/O WITH LID		DOCUMENT NO: 98ASA00465D		REV: 0	
		CASE NUMBER: 2290–01		10 MAY 2012	
		STANDARD: NON–JEDEC			